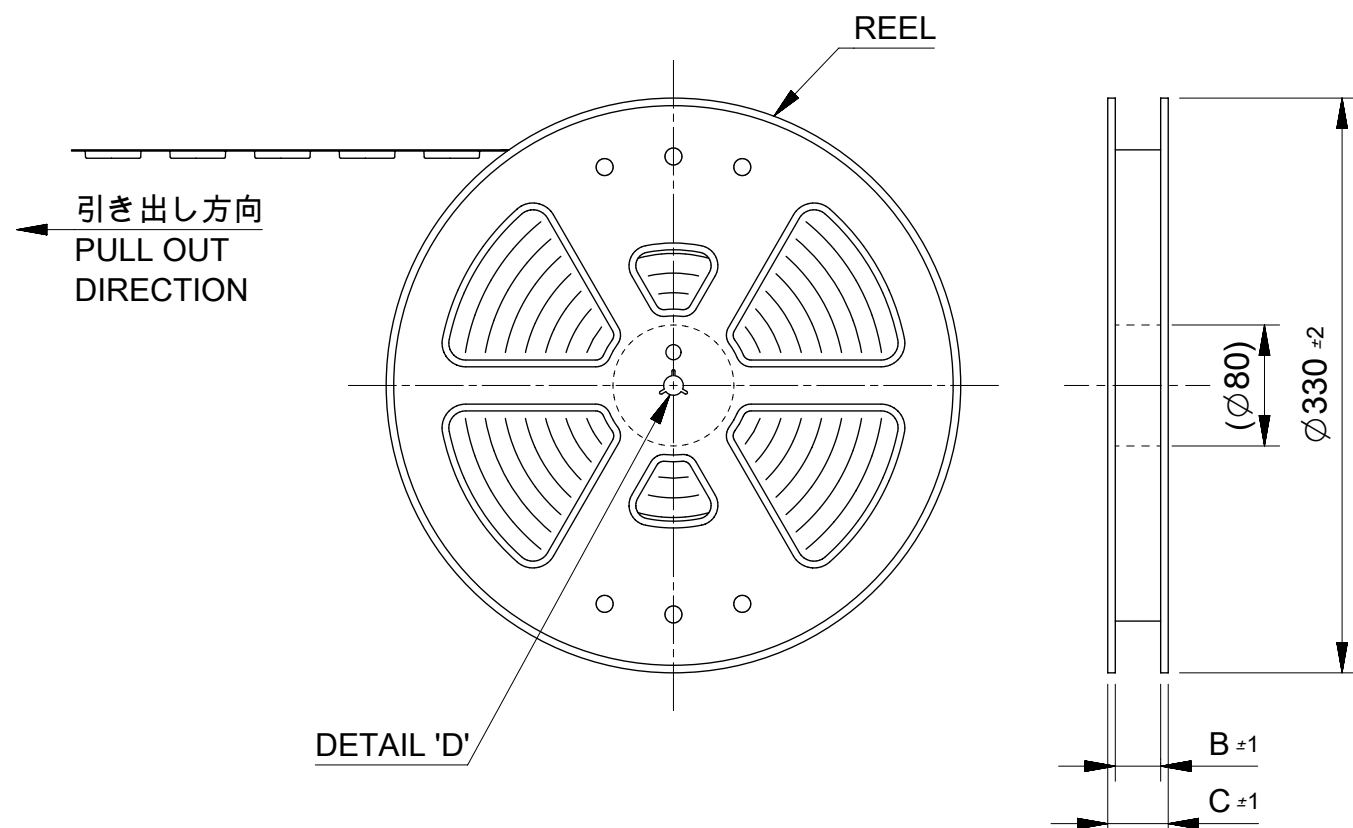
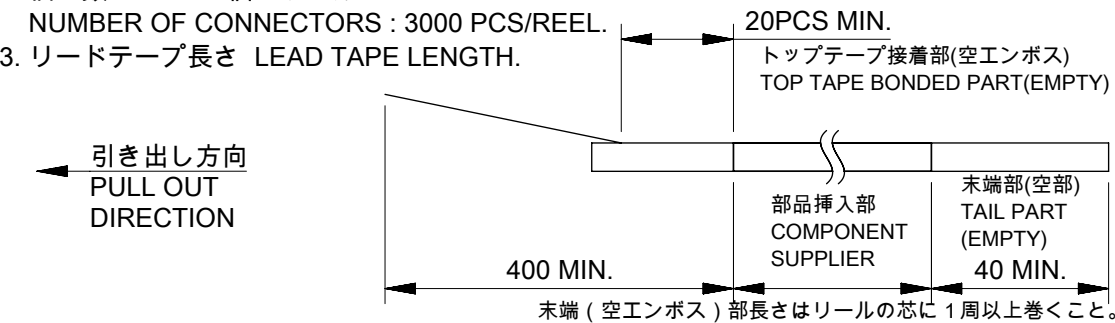


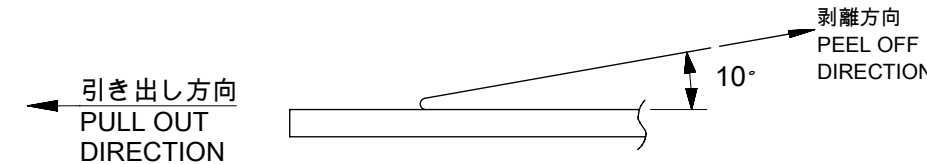


NOTES

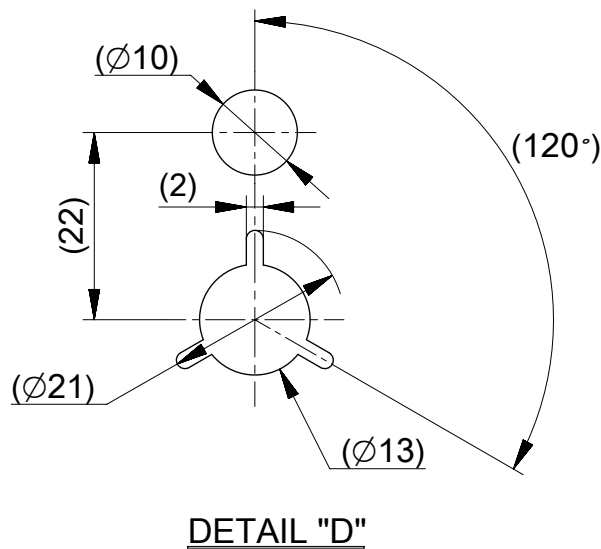
1. 製品詳細寸法については製品単体図面を参照下さい。
DETAIL DIMENSION SEE PRODUCT DRAWING.
2. 梱包数量：3000個 / リール
NUMBER OF CONNECTORS：3000 PCS/REEL.
3. リードテープ長さ LEAD TAPE LENGTH.



4. トップテープの剥離強度：0.1N~1.3N(10gf~130gf)
(剥離方向は下図参照)
尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE：0.1N~1.3N(10gf~130gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



5. 材料 MATERIAL
キャリアテープ (CARRIER TAPE)：ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE)：PET, OTHER
リール (REEL)：ポリスチレン (PS) [リサイクル材を含む]

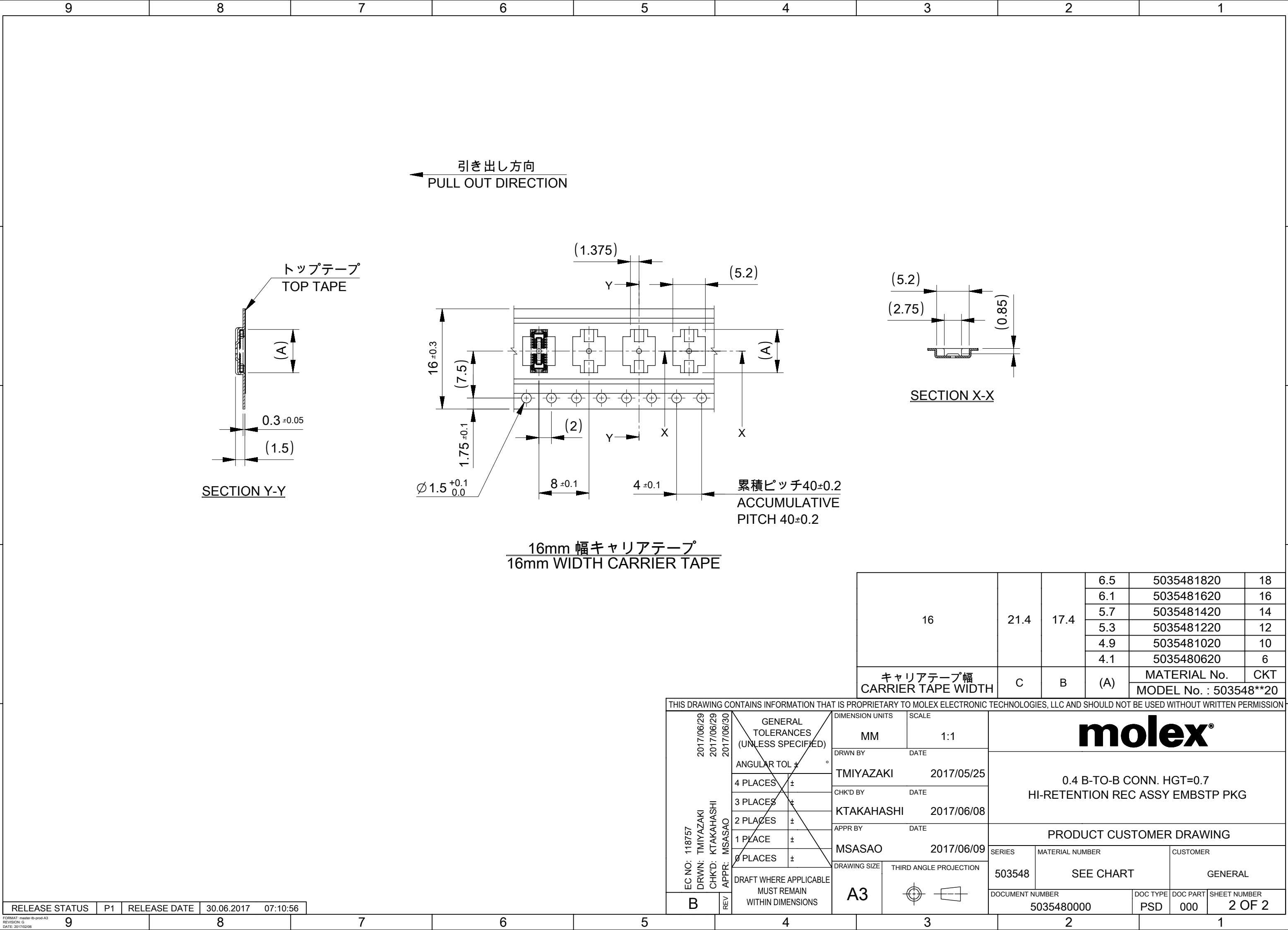


THIS DOCUMENT HAS BEEN RE-ISSUED BASED ON SD-503548-006, REV A

RELEASE STATUS P1 RELEASE DATE 30.06.2017 07:10:56

FORMAT: master-ib-prod-A3
REVISION: 5
DATE: 2017/02/08

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION												MODEL NO. : 503548**20					
EC NO: 118757 DRWN: TMIYAZAKI CHK'D: KTAKAHASHI APPR: MSASAO		2017/06/29 2017/06/29 2017/06/30		GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± ° 4 PLACES ± 3 PLACES ± 2 PLACES ± 1 PLACE ± 0 PLACES ±		DIMENSION UNITS		SCALE		molex® 0.4 B-TO-B CONN. HGT=0.7 HI-RETENTION REC ASSY EMBSTP PKG							
						MM		1:1									
						DRWN BY				DATE				PRODUCT CUSTOMER DRAWING SERIES 503548 MATERIAL NUMBER SEE SHEET 2 CUSTOMER GENERAL			
						TMIYAZAKI				2017/05/25							
						CHK'D BY				DATE							
						KTAKAHASHI				2017/06/08							
						APPR BY				DATE				DOCUMENT NUMBER 5035480000 DOC TYPE PSD DOC PART 000 SHEET NUMBER 1 OF 2			
						MSASAO				2017/06/09							
DRAWING SIZE				THIRD ANGLE PROJECTION													
B		REV		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		A3											



9 8 7 6 5 4 3 2 1

E

D

C

B

A

9 8 7 6 5 4 3 2 1

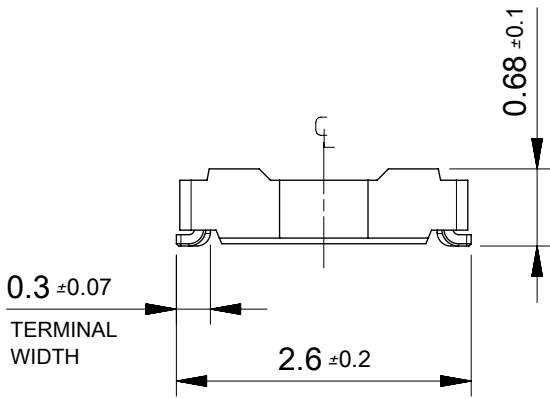
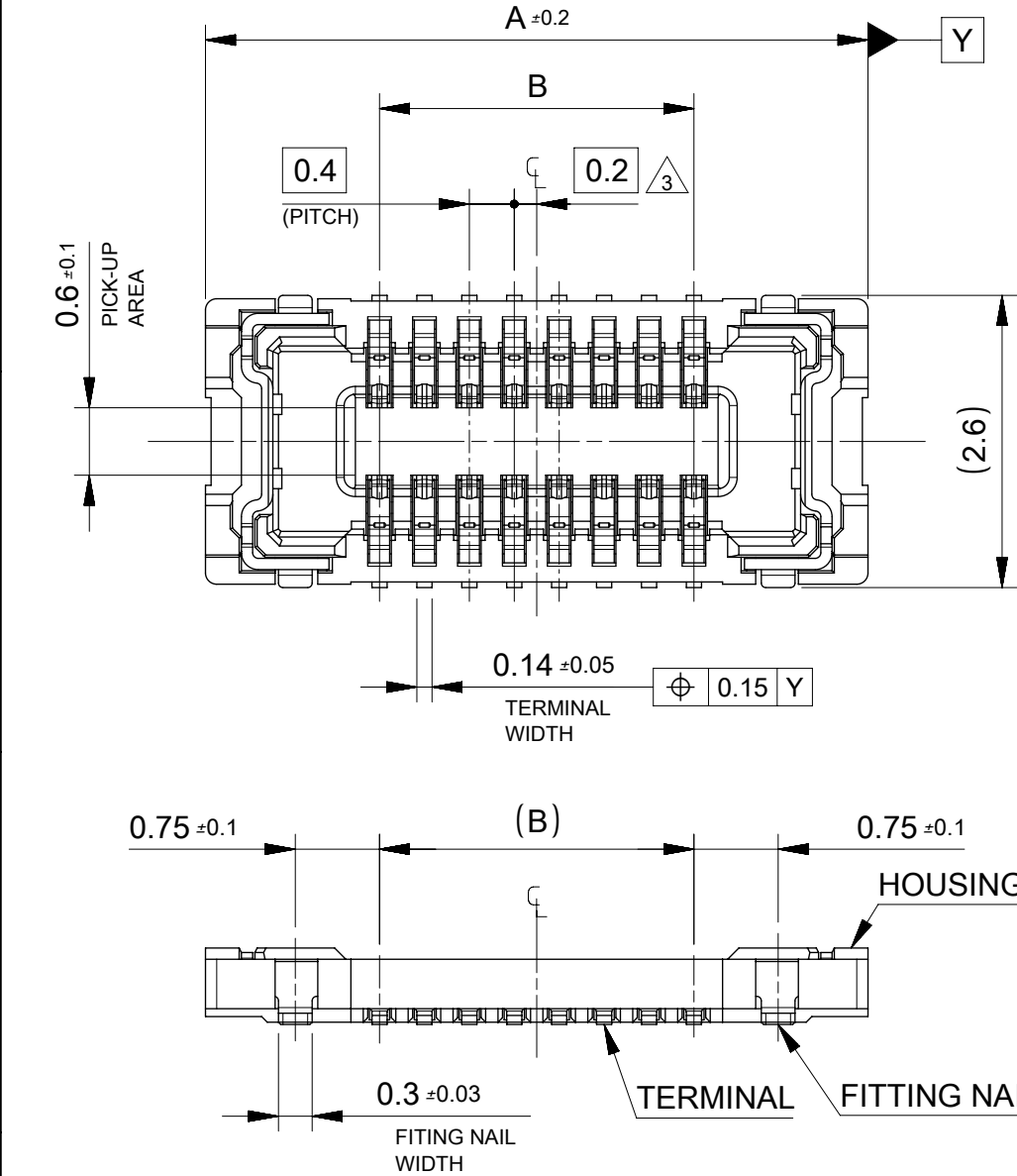
E

D

C

B

A



注記 NOTES

1. 使用材料 MATERIAL
ハウジング : 液晶ポリマー (LCP) UL94V-0 (黒)
HOUSING:LIQUID CRYSTAL POLYMER UL94V-0 (COLOR:BLACK)
ターミナル : 銅合金
TERMINAL : COPPER ALLOY
金具 : 銅合金
FITTING NAIL : COPPER ALLOY
2. メッキ仕様 PLATING
ターミナル TERMINAL
金メッキ GOLD
下地メッキ : ニッケルメッキ
UNDER PLATING : NICKEL
※コンタクト部とテール部の基板接触面には金メッキを施してあります。
それ以外の箇所は金メッキもしくはニッケルメッキが露出し、
外観上 色調が異なる場合がありますが、性能には影響ありません。
但し、コンタクト部とテール部の間にはニッケルメッキで金メッキを分断している箇所があります。
CONTACT AREA : GOLD PLATING
SOLDER TAIL AREA (PWB CONTACT SURFACE SIDE ONLY) : GOLD PLATING
OTHER AREAS : GOLD PLATING OR NICKEL PLATING
NICKEL PLATING DIVIDES BETWEEN THE CONTACT AREA (GOLD PLATING)
AND SOLDER TAIL AREA (GOLD PLATING).
- 金具 FITTING NAIL
金メッキ (テール部のみ) GOLD (ONLY TAIL PART)
下地メッキ : ニッケルメッキ
UNDER PLATING : NICKEL
- △3 (全極数 / 2) = 偶数の場合に適用。
APPLY FOR (CIRCUIT/2)=EVEN.
4. 嵌合相手 : 503552 シリーズ
MATE WITH : 503552 SERIES.
5. テール平坦度は、0.08 以下
テール及び金具の平坦度は、0.1 以下
TAIL COPLANARITY TO BE 0.08MAXIMUM.
TAIL AND FITTING NAIL COPLANARITY TO BE 0.1MAXIMUM.

3.2±0.2	6.3	5035481820	18
2.8±0.2	5.9	5035481620	16
2.4±0.2	5.5	5035481420	14
2.0±0.2	5.1	5035481220	12
1.6±0.2	4.7	5035481020	10
0.8±0.1	3.9	5035480620	6
B	A	EMBOSSED PACKAGE	
		オーダー番号 ORDER No.	極数 CIRCUITS
		CONNECTOR SERIES No. : 503548**19	

THIS DOCUMENT HAS BEEN RE-ISSUED BASED ON SD-503548-005, REV A

RELEASE STATUS	P1	RELEASE DATE	30.06.2017	07:11:00
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FORMAT: master-ib-prod-A3
REVISION: G
DATE: 2017/02/08

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EC NO: 118757
DRWN: TMIYAZAKI
CHK'D: KTAKAHASHI
APPR: MSASAO

2017/06/29
2017/06/29
2017/06/30

GENERAL TOLERANCES (UNLESS SPECIFIED)
ANGULAR TOL ± 1.0 °
4 PLACES ±
3 PLACES ±
2 PLACES ±
1 PLACE ±
0 PLACES ±

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION UNITS
MM

DRWN BY
TMIYAZAKI

CHK'D BY
KTAKAHASHI

APPR BY
MSASAO

DRAWING SIZE
A3

SCALE
15:1

DATE
2017/05/25

DATE
2017/06/08

DATE
2017/06/09

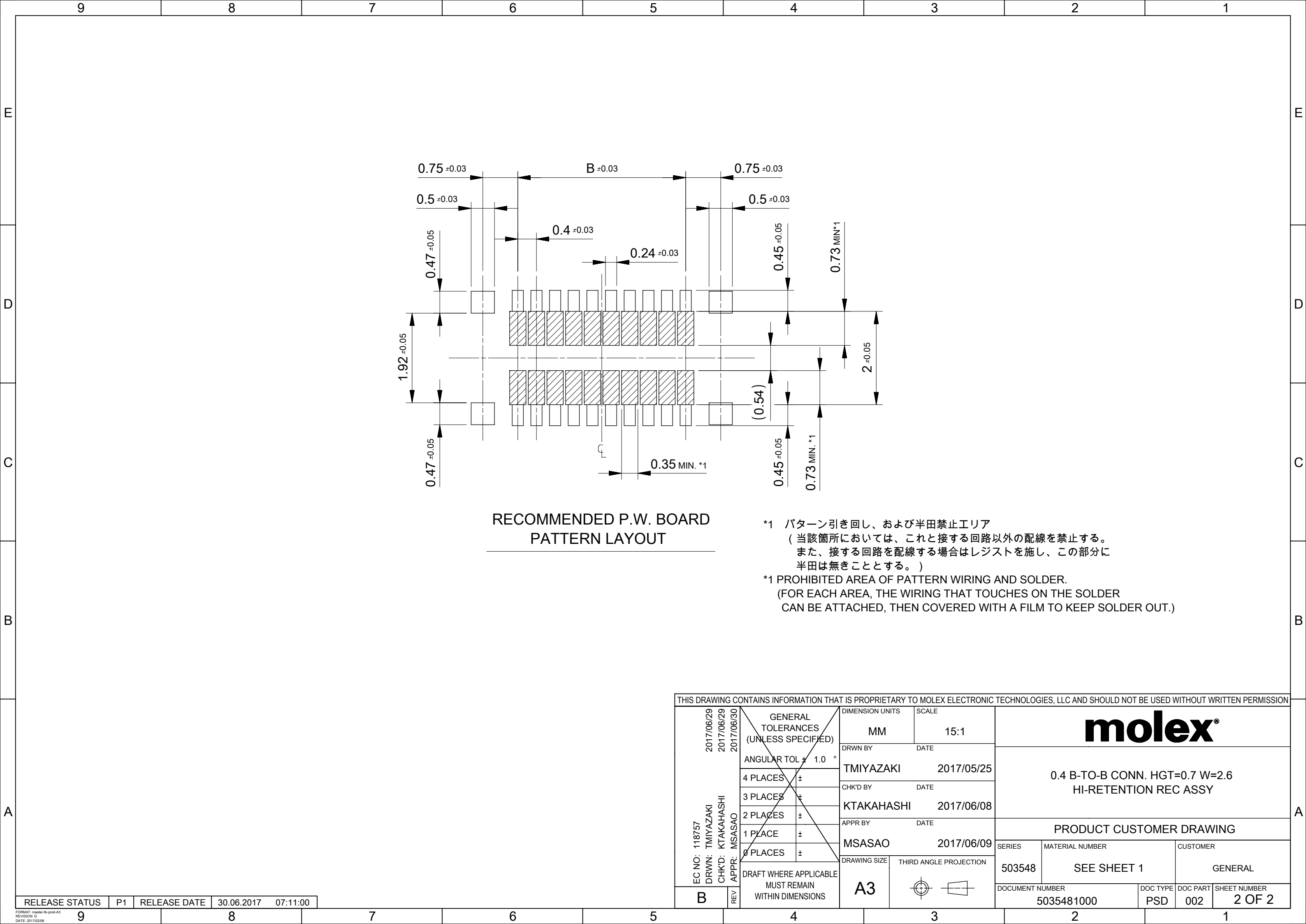
THIRD ANGLE PROJECTION

molex®

0.4 B-TO-B CONN. HGT=0.7 W=2.6
HI-RETENTION REC ASSY

PRODUCT CUSTOMER DRAWING

SERIES 503548	MATERIAL NUMBER SEE CHART	CUSTOMER GENERAL
DOCUMENT NUMBER 5035481000	DOC TYPE PSD	DOC PART 002
SHEET NUMBER 1 OF 2		



RECOMMENDED P.W. BOARD
PATTERN LAYOUT

- *1 パターン引き回し、および半田禁止エリア
(当該箇所においては、これと接する回路以外の配線を禁止する。
また、接する回路を配線する場合はレジストを施し、この部分に
半田は無きこととする。)
- *1 PROHIBITED AREA OF PATTERN WIRING AND SOLDER.
(FOR EACH AREA, THE WIRING THAT TOUCHES ON THE SOLDER
CAN BE ATTACHED, THEN COVERED WITH A FILM TO KEEP SOLDER OUT.)

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		MM		15:1									
		DRWN BY		DATE		PRODUCT CUSTOMER DRAWING							
		TMIYAZAKI		2017/05/25									
		CHK'D BY		DATE		SERIES MATERIAL NUMBER CUSTOMER							
		KTAKAHASHI		2017/06/08									
		APPR BY		DATE		DOCUMENT NUMBER DOC TYPE DOC PART SHEET NUMBER							
		MSASAO		2017/06/09									
B	REV	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWING SIZE		THIRD ANGLE PROJECTION		503548		SEE SHEET 1		GENERAL	
				A3				5035481000		PSD		002	